# **Bondline 700**

## **Thermal Adhesive Tape**

**Bondline 700** is an electrically isolating thermal adhesive tape designed to mechanically fix and thermally connect electronic devices and FR4 PCBs to a



heatsinkFormulated from acrylic, **Bondline 700** is pressure sensitive and the differing thicknesses conform to varying surface textures which fills micro-air voids between contact surfaces and reduces thermal resistance. **Bondline 700** is developed for applications requiring good thermal transfer, dielectric strength and permanent adhesion.

## **Features**

- Electrically isolating, acrylic thermal tape
- Conformability fills micro air voids between mating surfaces reducing thermal resistance
- Allows sufficient heat exchange between component and cooling mechanism

## **Availability**

- Available in standard thicknesses of 0.15mm, 0.25mm and 0.5mm
- Supplied on 30m to 50m rolls and to specified widths on request
- Available as custom kiss-cut parts on rolls for starboards and as die-cut custom shapes

#### **Typical Physical Properties**

Property (unit)	Test Method	Bondline 700 (0.25mm)
Colour	Visual	White
Thermal Conductivity (W/mK)	ASTM D5470	1.1
Thermal Resistance (K-cm²/W)	ASTM D5470	3
Operating Temp (°C)	In House	-25 to +130

## **Benefits**

- Provides excellent adhesion between a variety of substrates
- Delivers a permanent mechanical bond with high dielectric strength
- · Simple to handle and apply

## **Recommended Uses**

- Mounting high and mid-power LED modules to a heatsink
- To provide a fast and consistent method of attaching power components to a heat sink

#### **Electrical and Mechanical Information**

Property (unit)	Test Method	Bondline 700 (0.25mm)
Shear Adhesion (kg/cm²)	ASTM D-1002	3.5
Tensile Strength (Kg/cm)	ASTM 412	0.15
Breakdown Voltage (Volts AC)	ASTM D149	>6000
Elongation (%)	ASTM 412	400
Flame Rating	UL94	V2



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